

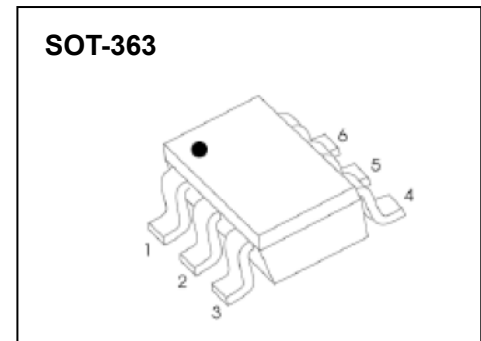
FEATURE

- Surface Mount Package
- Low $R_{DS(on)}$
- Operated at Low Logic Level Gate Drive
- ESD Protected Gate
- Including a N-ch CJ3134K and a P-ch CJ3139K (independently) In a Package

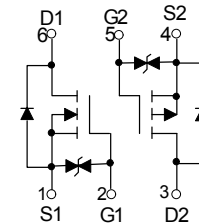
APPLICATION

- Load/ Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
20V	400m Ω @4.5V	0.75A
	600m Ω @2.5V	
	800m Ω @1.8V	
-20V	750m Ω @-4.5V	-0.66A
	800m Ω @-2.5V	
	1000m Ω (TYP)@-1.8V	



Equivalent Circuit



MARKING



ABSOLUTE MAXIMUM RATINGS ($T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
N-MOSFET			
Drain-Source Voltage	V_{DS}	20	V
Typical Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current (note 1)	I_D	0.75	A
Pulsed Drain Current ($t_p=10\mu\text{s}$)	I_{DM}	1.8	A
P-MOSFET			
Drain-Source Voltage	V_{DS}	-20	V
Typical Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current (note 1)	I_D	-0.66	A
Pulsed Drain Current ($t_p=10\mu\text{s}$)	I_{DM}	-1.2	A
Temperature and Thermal Resistance			
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	833	$^{\circ}\text{C}/\text{W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^{\circ}\text{C}$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T_L	260	$^{\circ}\text{C}$

**N-ch MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	20	27		V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±10V, V _{DS} = 0V			±20	uA
Gate threshold voltage (note 2)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.35		1.1	V
Drain-source on-resistance(note 2)	R _{DS(on)}	V _{GS} =4.5V, I _D =0.65A		260	400	mΩ
		V _{GS} =2.5V, I _D =0.55A		350	600	mΩ
		V _{GS} =1.8V, I _D =0.45A		600	800	mΩ
Forward tranconductance(note 2)	g _{FS}	V _{DS} =10V, I _D =0.8A		1.6		S
Diode forward voltage	V _{SD}	I _S =0.15A, V _{GS} = 0V			1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} =16V, V _{GS} =0V, f =1MHz		79	120	pF
Output Capacitance	C _{oss}			13	20	pF
Reverse Transfer Capacitance	C _{rss}			9	15	pF
SWITCHING CHARACTERISTICS (note 3,4)						
Turn-on delay time	t _{d(on)}	V _{GS} =4.5V, V _{DS} =10V, I _D =500mA, R _{GEN} =10Ω		6.7		ns
Turn-on rise time	t _r			4.8		ns
Turn-off delay time	t _{d(off)}			17.3		ns
Turn-off fall time	t _f			7.4		ns

P-ch MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =-250μA	-20	-27		V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-20V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±10V, V _{DS} = 0V			±20	uA
Gate threshold voltage (note 2)	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.35		-1.1	V
Drain-source on-resistance(note 2)	R _{DS(on)}	V _{GS} =-4.5V, I _D =-1A		460	700	mΩ
		V _{GS} =-2.5V, I _D =-0.8A		600	850	mΩ
		V _{GS} =-1.8V, I _D =-0.5A		1000		mΩ
Forward tranconductance(note 2)	g _{FS}	V _{DS} =-10V, I _D =-0.54A		1.2		S
Diode forward voltage	V _{SD}	I _S =-0.5A, V _{GS} = 0V			-1.2	V
DYNAMIC CHARACTERISTICS (note 4)						
Input Capacitance	C _{iss}	V _{DS} =-16V, V _{GS} =0V, f =1MHz		113	170	pF
Output Capacitance	C _{oss}			15	25	pF
Reverse Transfer Capacitance	C _{rss}			9	15	pF
SWITCHING CHARACTERISTICS (note 3, 4)						
Turn-on delay time	t _{d(on)}	V _{GS} =-4.5V, V _{DS} =-10V, I _D =-200mA, R _{GEN} =10Ω		9		ns
Turn-on rise time	t _r			5.8		ns
Turn-off delay time	t _{d(off)}			32.7		ns
Turn-off fall time	t _f			20.3		ns

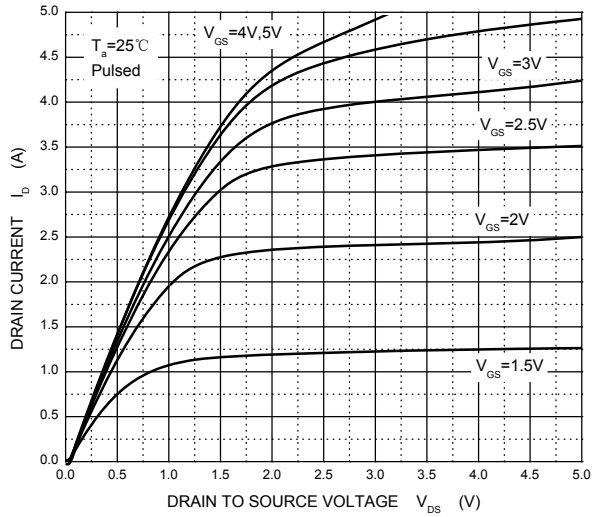
Notes :

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse width=300μs, duty cycle≤2%.
3. Switching characteristics are independent of operating junction temperature.
4. Granted by design, not subject to producing.

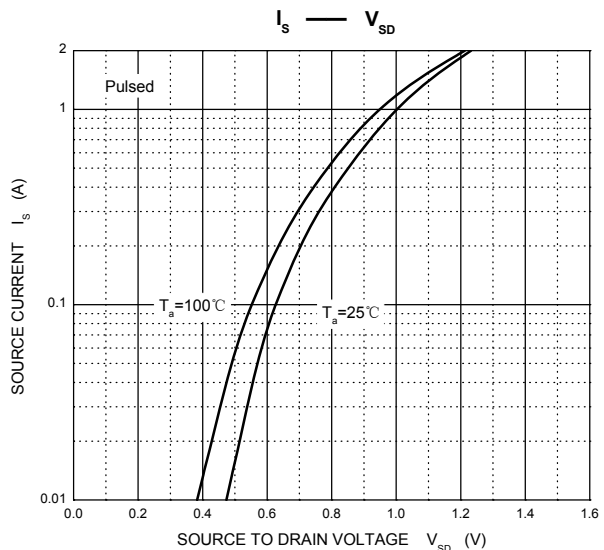
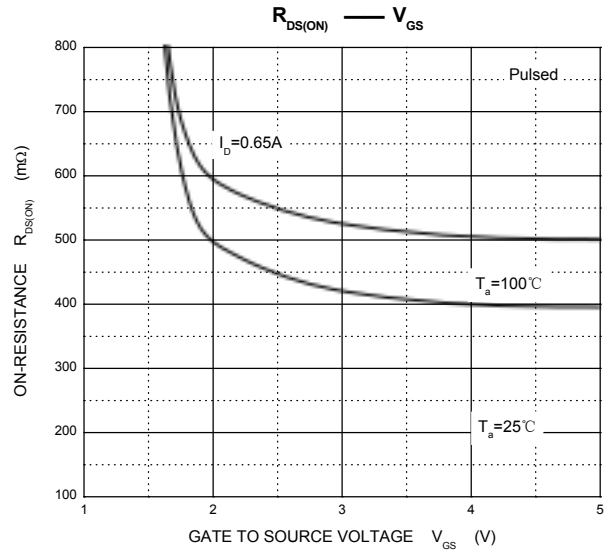
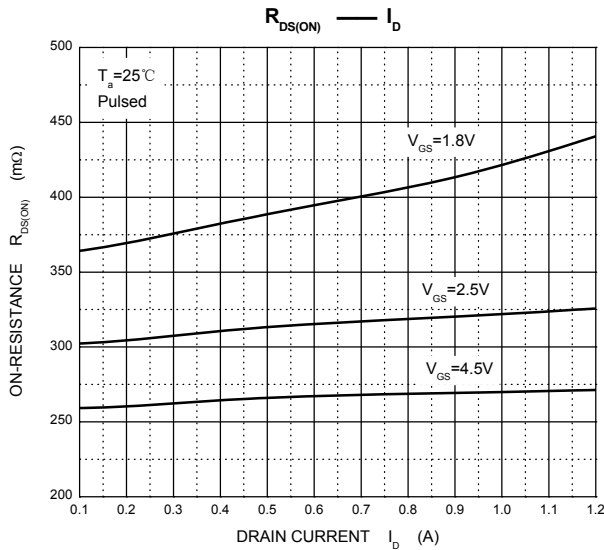
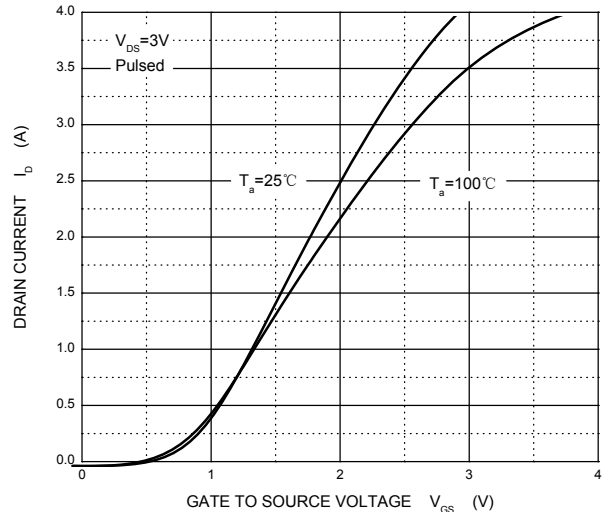
Typical Characteristics

N-Channel MOS

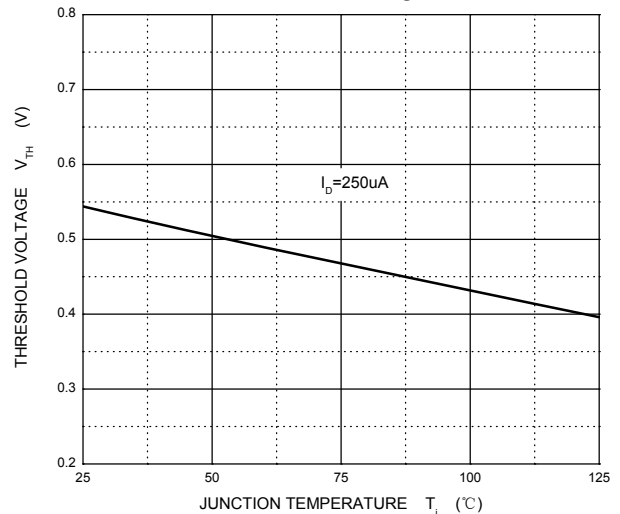
Output Characteristics



Transfer Characteristics



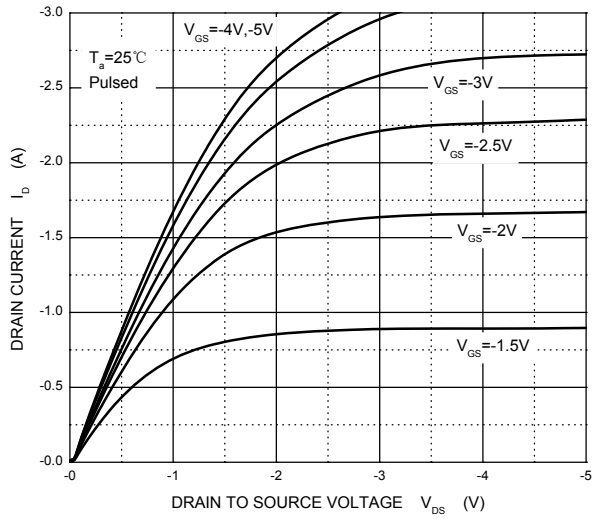
Threshold Voltage



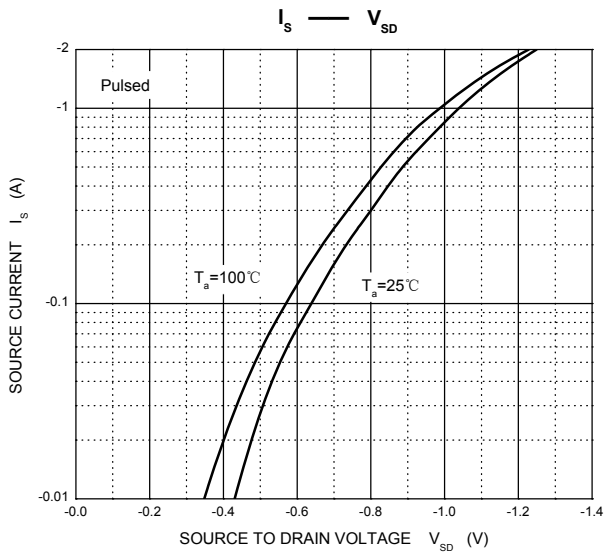
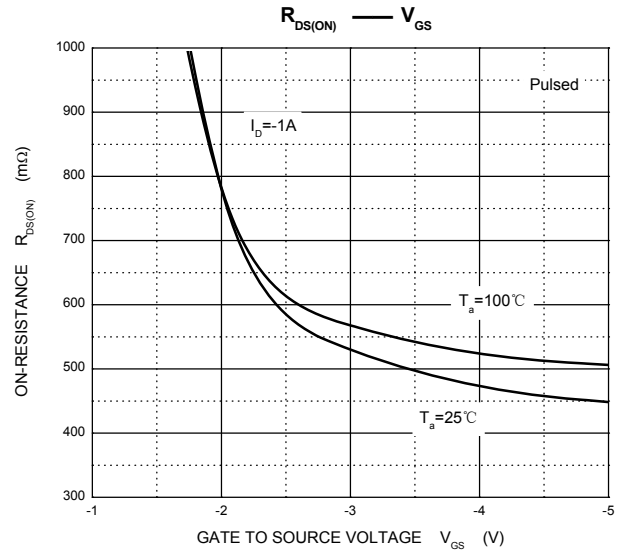
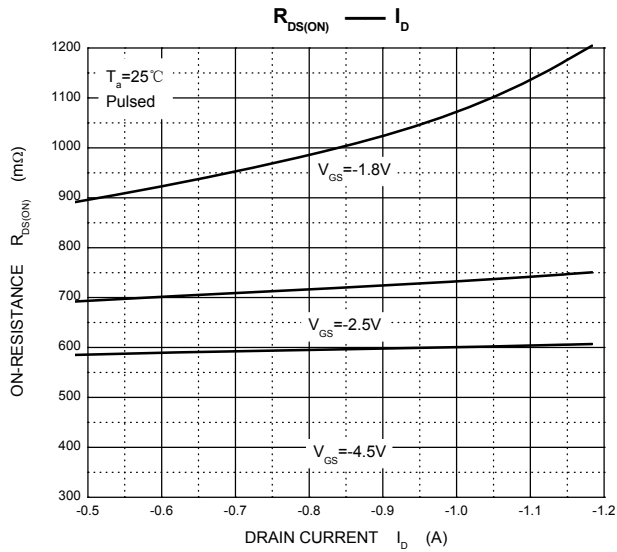
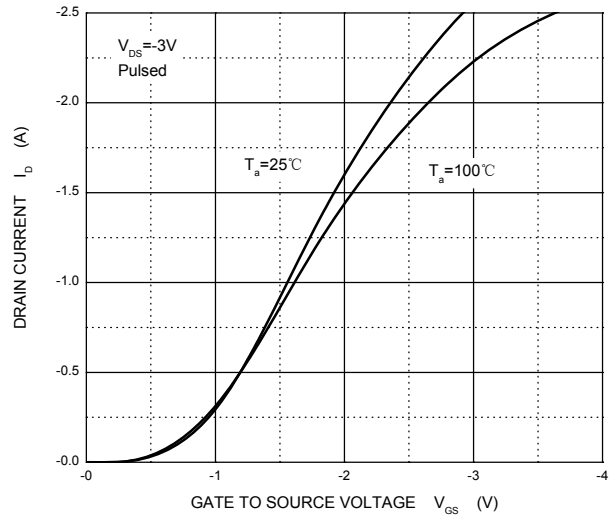
Typical Characteristics

P-Channel MOS

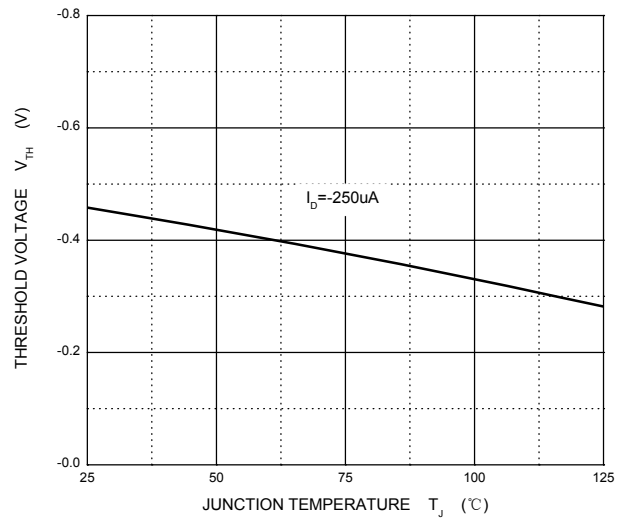
Output Characteristics



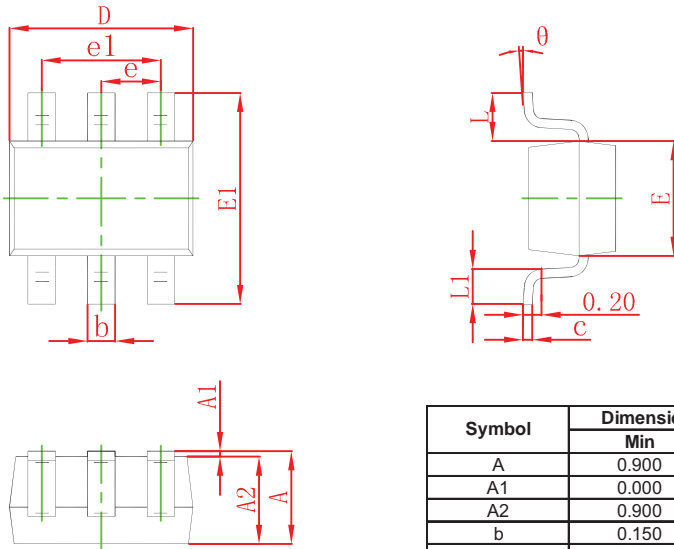
Transfer Characteristics



Threshold Voltage

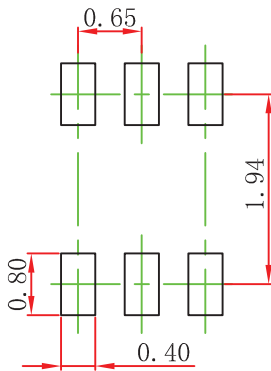


SOT-363 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.100	0.150	0.004	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.400	0.085	0.094
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
theta	0°	8°	0°	8°

SOT-363 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.